

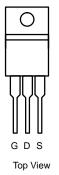
RoHS

COMPLIANT

N-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY				
V _{(BR)DSS} (V)	r _{DS(on)} (Ω)	I _D (A) ^a		
20	$0.004@V_{GS} = 4.5V$	100		
20	0.005@ V _{GS} = 2.5 V	95		



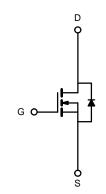


FEATURES

- TrenchFET[®] Power MOSFET
- 100 % R_g and UIS Tested
 Compliant to RoHS Directive 2011/65/EU

APPLICATIONS

- OR-ing
- Server •
- DC/DC ٠



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25° C UNLESS OTHERWISE NOTED)					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	20	v	
Gate-Source Voltage		V _{GS}	±12	- v	
Continuous Drain Current (T ₁ = 175°C)	T _C = 25°C	I-	100		
Continuous Drain Current (1) = 173 C)	T _C = 100°C		85	A	
Pulsed Drain Current		I _{DM}	260		
Avalanche Current		I _{AR}	35		
Repetitive Avalanche Energy ^b	L = 0.1 mH	E _{AR}	45	mJ	
Power Dissipation	T _C = 25°C	PD	125 ^a	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
lunction to Ambient	PCB Mount (TO-263) ^c	D	40		
Junction-to-Ambient	Free Air (TO-220AB)	R _{thJA}	62.5	°C/W	
Junction-to-Case		R _{thJC}	1.25		

Notes:

a. See SOA curve for voltage derating.

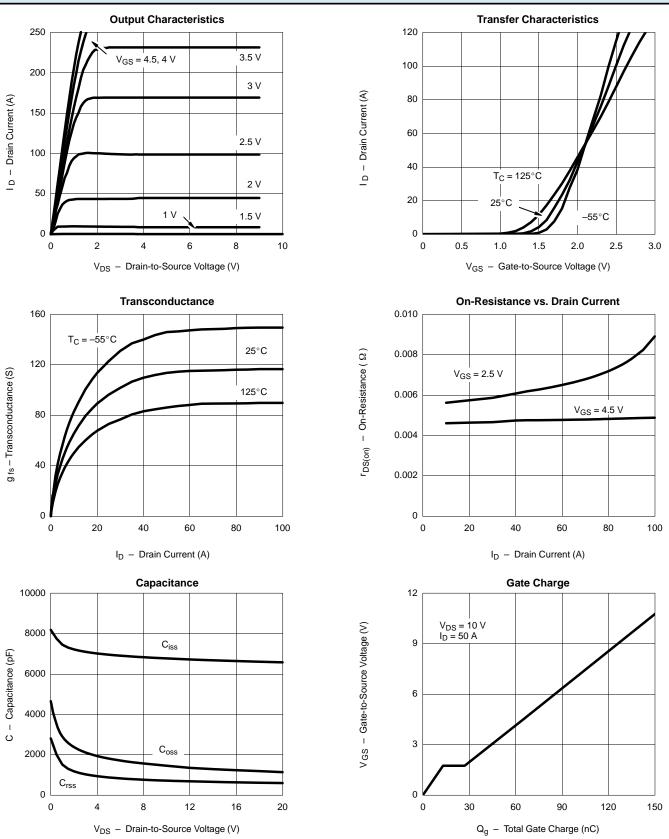
b. Duty cycle \leq 1%. c. When mounted on 1" square PCB (FR-4 material).



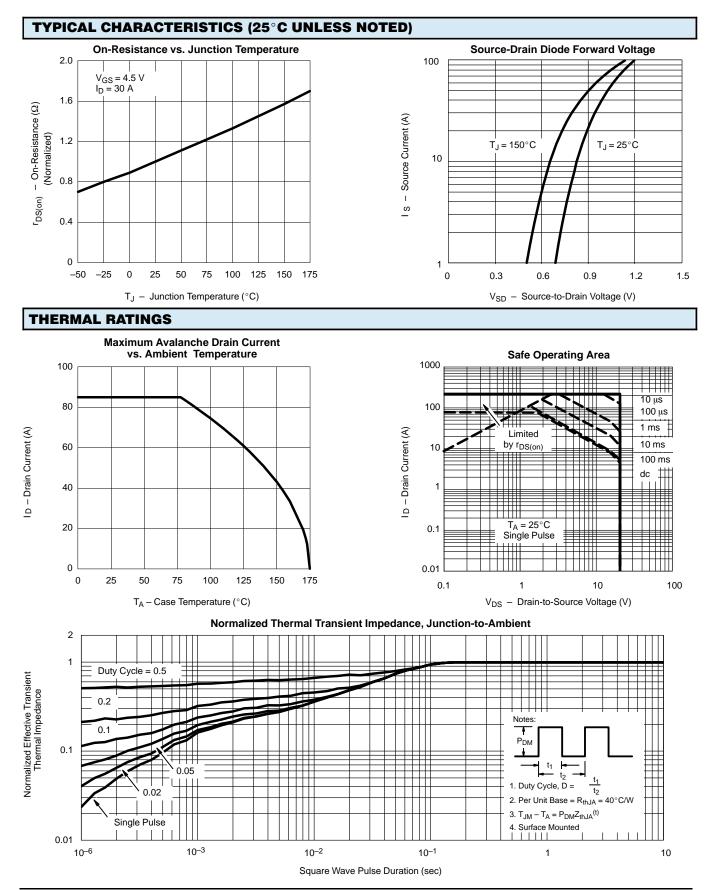
MOSFET SPECIFICATIONS (T _J =25°C UNLESS OTHERWISE NOTED)							
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I _D = 250 µA	20			v	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{DS} = 250 \ \mu A$	0.5		1.5	ľ	
Gate-Body Leakage	I _{GSS}	V_{DS} = 0 V, V_{GS} = \pm 12 V			±100	nA	
		$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125^{\circ}\text{C}$			50	μΑ	
		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175^{\circ}\text{C}$			150		
On-State Drain Current ^a	I _{D(on)}	V_{DS} = 5 V, V_{GS} = 4.5 V	120			Α	
		$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 30 \text{ A}$	0.004				
Desire Courses On Otate Desistences		$V_{GS} = 4.5 \text{ V}, I_D = 30 \text{ A}, T_J = 125^{\circ}\text{C}$	J = 125°C 0.007				
Drain-Source On-State Resistance ^a	r _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 30 \text{ A}, T_J = 175^{\circ}\text{C}$		0.010		Ω	
		$V_{GS} = 2.5 \text{ V}, \text{ I}_{D} = 20 \text{ A}$		0.005			
Forward Transconductancea	9 _{fs}	$V_{DS} = 5 V, I_D = 30 A$	20			S	
Dynamic ^b	1 1		•	•		•	
Input Capacitance	C _{iss}			6000		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 20 V, f = 1 MHz		1100			
Reversen Transfer Capacitance	C _{rss}			600			
Total Gate Charge ^c	Qg			65	130		
Gate-Source Charge ^c	Q _{gs}	V_{DS} = 10 V, V_{GS} = 4.5 V, I_{D} = 85 A		13		nC	
Gate-Drain Charge ^c	Q _{gd}			14		1	
Turn-On Delay Time ^c	t _{d(on)}			25	40	ns	
Rise Time ^c	tr	V_{DD} = 10 V, R _L = 0.12 Ω I _D \simeq 85 A, V _{GEN} = 4.5 V, R _G = 2.5 Ω		120	180		
Turn-Off Delay Time ^c	t _{d(off)}			80	120		
Fall Time ^c	t _f			100	150		
Source-Drain Diode Ratings a	nd Characteristic	cs (T _C = 25°C) ^b					
Pulsed Current	I _{SM}				240	A	
Forward Voltage ^a	V _{SD}	$I_{F} = 100 \text{ A}, \text{ V}_{GS} = 0 \text{ V}$		1.2	1.5	V	
Reverse Recovery Time	t _{rr}	I _F = 50 A, di/dt = 100 A/μs		45	100	ns	



TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

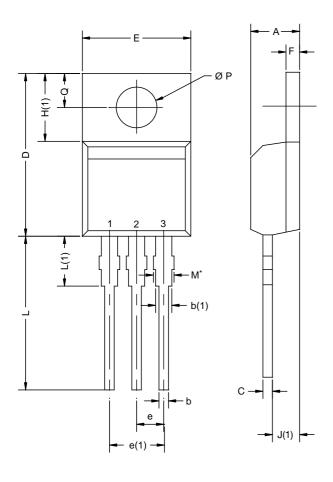








TO-220AB



	MILLIMETERS		INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: X12-0208-Rev. N, 08-Oct-12 DWG: 5471					

Notes

 * M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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